

### **REMARKS**

Claims 1-13 are pending in the present application.

Claim 1 is currently amended to clarify the claimed invention.

Claims 7-13 are newly entered. A Fee Transmittal is submitted herewith.

No new matter is entered as a result of the amendments.

The claims are believed to be allowable for the reasons set forth herein. Notice thereof is respectfully requested.

#### Claim Rejections 35 USC § 112

Claims 1-6 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Claim 1 originally recited "elevated temperature" which was replaced with "high temperature" in the previous action. The recitation "high temperature" was considered to be vague. As set forth throughout the specification the term "elevated temperature" refers to a temperature which is elevated relative to ambient temperature. In an effort to advance the application to allowance the claim has been clarified in accordance with the specification.

Particular reference is made to paragraph [0012] wherein the intent of the recitation is clearly set forth. No new matter is entered and the rejection is rendered moot.

Claim Rejections - 35 USC § 103

Claims 1 and 3-6 are rejected under 35 U.S.C. 103(a) as being unpatentable over Ogino et al. (USPN 6,236,561) in view of Hernandez (USPN 4,594,641) or Knecht et al. (USPN 5,640,746).

Ogino et al. is cited as disclosing a method of manufacturing a solid electrolytic capacitor. The Office admits that Ogino et al. fails to disclose applying a pre-coat resin to a portion of the capacitor terminals.

Hernandez is cited as disclosing those features lacking in Ogino et al. and, specifically, a resin which is flexible above ambient temperatures. Applicants respectfully disagree based on the fact that there is no such teaching in Hernandez et al.

In the "Response to Applicants Arguments" the Office opines that the polymeric resin of Knecht is rigid at ambient temperature and flexible at higher temperature at least until fully cured. Applicants respectfully request that this position be supported. Presently, there is no teaching to suggest that a

partially cured resin is rigid at ambient temperature and flexible at higher temperature. Even assuming, *arguendo*, that one can derive such a reading this would be inconsistent with the teachings of both Hernandez and Knecht.

At col. 5 line 9 Hernandez teaches that the layers are heat tacked and hot press laminated prior to subsequent assembly. One of skill in the art would not anticipate this to indicate a partial curing. The process is repeated later in the same column. Similarly, Knecht teaches full curing as a major step at col. 6 lines 24-31. The position of the Office is contrary to that recited in the reference relied on. Even if one did read either Hernandez or Knecht to teach partial curing, in direct contradiction to the actual teachings, they would have no basis to predict that the partially cured resin would be rigid at ambient temperature and flexible at higher temperatures. Neither Hernandez nor Knecht even mention the flexibility and therefore any limitation must be provided by the reader based solely on the teachings provided in the present application.

Knecht is cited as an alternative to Hernandez. As stated previously Knecht specifically recites that the interlayer is resistant to high temperature. One of skill in the art would not consider a material with temperature specific flexibility to

be equivalent to one which is resistant to high temperature as set forth in Knecht. This equivalency is only possible in hindsight based on the present specification and, even then, it is contrary to the teachings recited.

In summary, Ogino et al. lacks teachings of critical elements of claim 1 as set forth by the Office. Hernandez and Knecht do not provide those teachings which are otherwise lacking in Ogino et al. Therefore, Claim 1 represents a patentable advance in the art.

Claims 3-6 depend from claim 1 and are patentable for, at least, the same reasons as claim 1.

Applicants respectfully request that the rejection of claims 1 and 3-6 be withdrawn as being improperly based on art which neither teaches the claimed invention nor leads one of skill in the art in a direction to ultimately attempt the claimed invention.

Claim 2 is rejected under 35 U.S.C. 103(a) as being unpatentable over Ogino et al. in view of Hernandez or Knecht,

as applied above, and further in view of Hayase et al. (USPN 6,686,085).

Ogino et al., Hernandez and Knecht are discussed above and all arguments presented above are applicable herein equally.

The Office admits that Ogino et al., Hernandez and Knecht fail to recite liquid epoxy resins containing lactones. Hayase is cited as providing those teachings that are otherwise lacking.

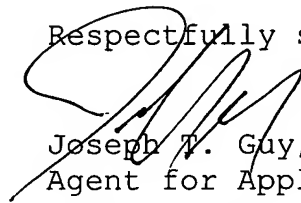
Hayase is directed to a chemical battery and therefore provides no guidance regarding a method for manufacturing a capacitor. Teachings related to a liquid resin containing lactones may be of interest, in hindsight, but this teaching does not mitigate the deficiencies of the primary references with which it is combined. One of skill in the art would be no better prepared to manufacture a capacitor in a manner set forth in claim 1 after referring to Hayase. Even if a lactone were considered, in hindsight, one of skill in the art would have no motivation for contemplating the use of lactones as a pre-coat since the primary references do not teach a precoat and Hayase provides no guidance or suggestion that one would be beneficial in the manufacture of capacitors.

The rejection of claim 2 is traversed and notice thereof is respectfully requested.

#### CONCLUSIONS

Claims 1-13 are pending in the present application. All claims are believed to be in condition for allowance. Notice thereof is respectfully requested.

Respectfully submitted,



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